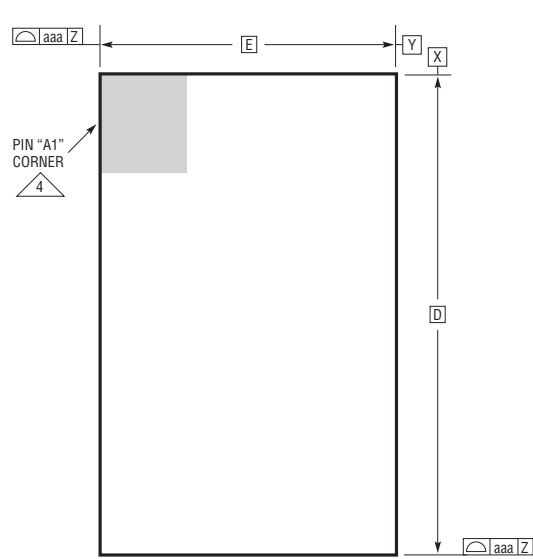
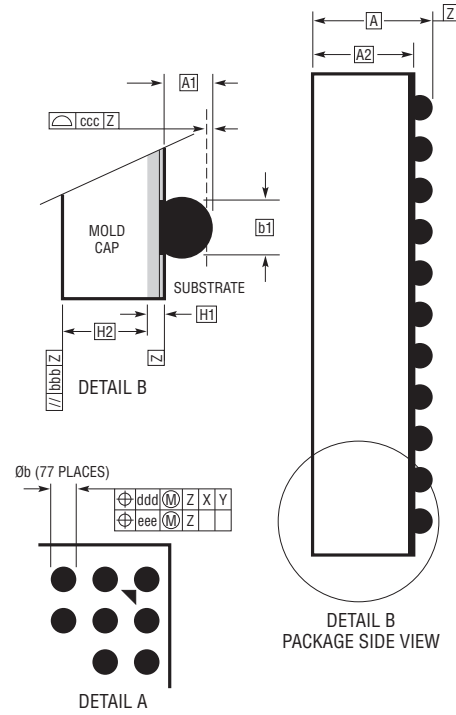


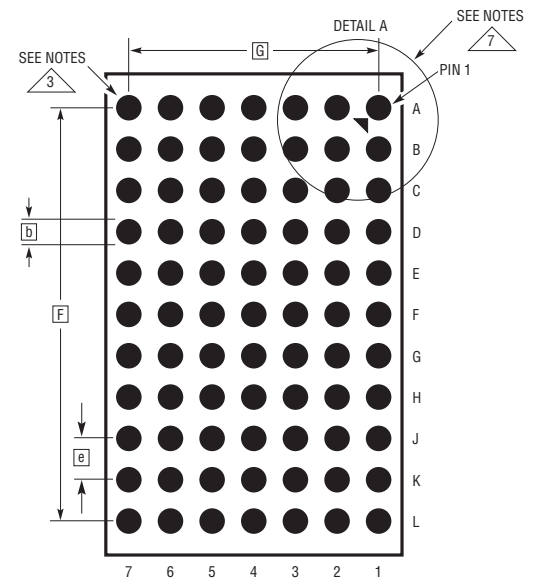
**BGA Package**  
**77-Lead (15.00mm × 9.00mm × 2.42mm)**  
 (Reference LTC DWG# 05-08-1559 Rev 0)



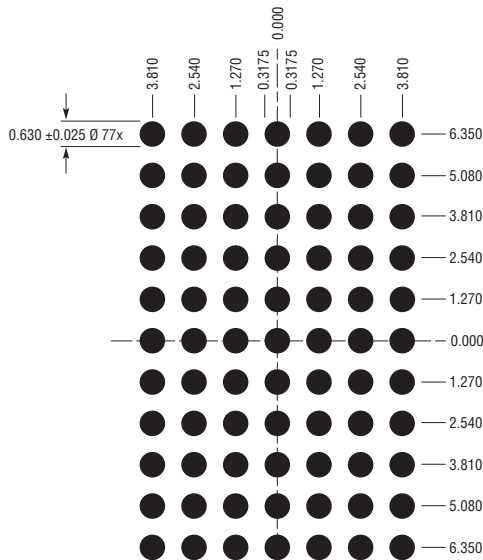
PACKAGE TOP VIEW



DETAIL B  
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



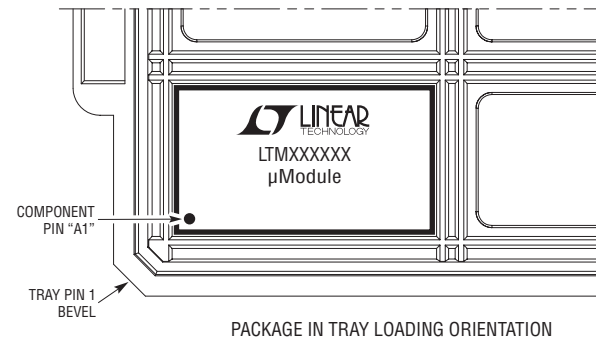
SUGGESTED PCB LAYOUT  
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.22	2.42	2.62	
A1	0.50	0.60	0.70	
A2	1.72	1.82	1.92	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D		15.00		
E		9.00		
e		1.27		
F		12.70		
G		7.62		
H1	0.27	0.32	0.37	
H2	1.45	1.50	1.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 77

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
- 3 BALL DESIGNATION PER JESD MS-028 AND JEP95
- 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
- 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION